

SOT240-1

plastic dual in-line package; 48 leads (600 mil)

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	DIP48
Package type industry code	DIP48
Package style descriptive code	DIP (dual in-line package)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MS-011
Mounting method type	T (through-hole mount)
Issue date	13-2-2003

Table 1. Package summary

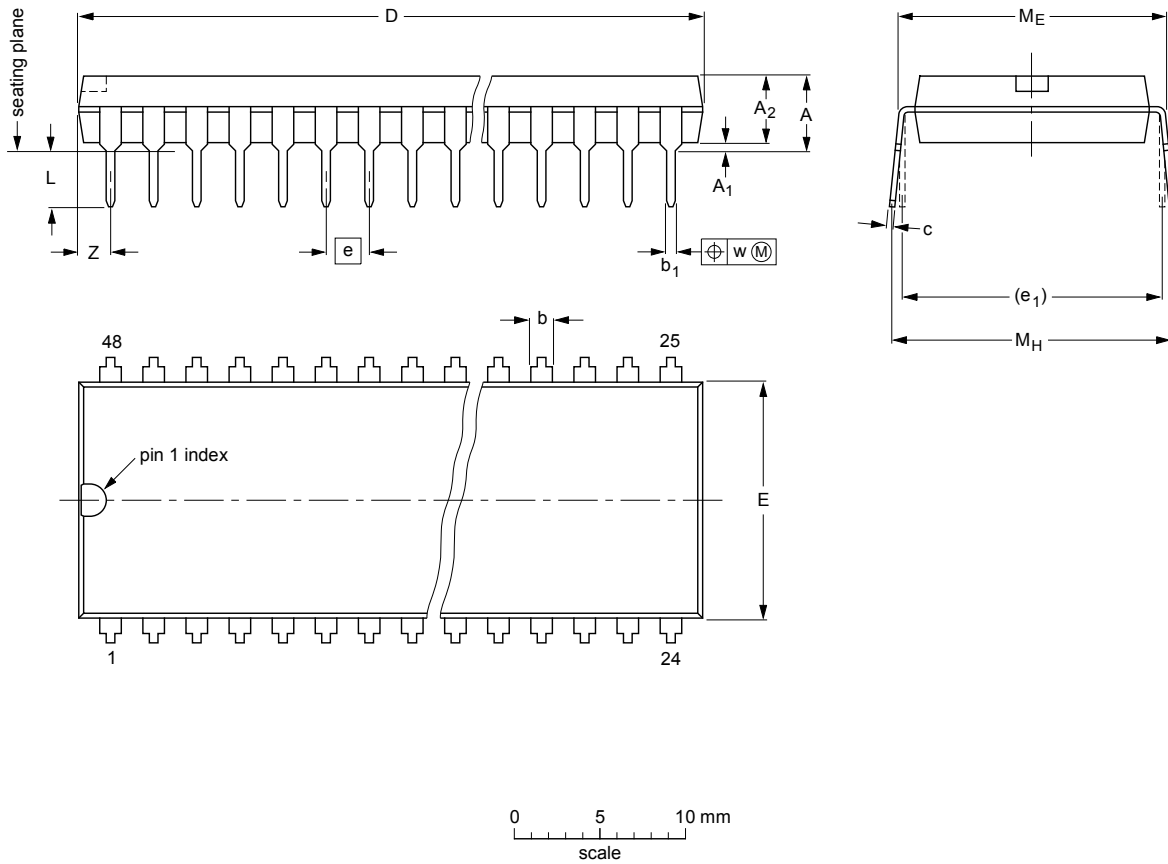
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	61.6	-	62.1	62.6	mm
E	package width	13.56	-	13.9	14.22	mm
A	seated height	[tbd]	-	4.9	4.9	mm
A ₂	package height	[tbd]	-	4.06	4.06	mm
n ₂	actual quantity of termination	-	-	48	-	



2. Package outline

DIP48: plastic dual in-line package; 48 leads (600 mil)

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DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁ min.	A ₂ max.	b	b ₁	c	D ⁽¹⁾	E ⁽¹⁾	e	e ₁	L	M _E	M _H	w	Z ⁽¹⁾ max.
mm	4.9	0.36	4.06	1.4 1.14	0.53 0.38	0.36 0.23	62.6 61.6	14.22 13.56	2.54	15.24	3.90 3.05	15.88 15.24	18.46 15.24	0.254	2.1
inches	0.19	0.014	0.16	0.055 0.045	0.021 0.015	0.014 0.009	2.46 2.42	0.56 0.53	0.1	0.6	0.15 0.12	0.63 0.60	0.73 0.60	0.01	0.083

Note

1. Plastic or metal protrusions of 0.25 mm (0.01 inch) maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT240-1		MS-011				99-12-27 03-02-13

Fig. 1. Package outline DIP48 (SOT240-1)

3. Legal information

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